



BYV25F-600

Enhanced ultrafast power diode

Rev. 02 — 7 March 2011

Product data sheet

1. Product profile

1.1 General description

Enhanced ultrafast power diode in a SOD59 (2-lead TO-220AC) plastic package.

1.2 Features and benefits

- High thermal cycling performance
- Low on-state losses
- Low thermal resistance
- Soft recovery characteristic

1.3 Applications

- Dual Mode (DCM and CCM) PFC
- Power Factor Correction (PFC) for Interleaved Topology

1.4 Quick reference data

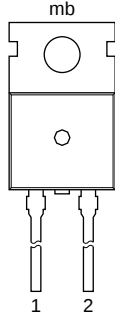
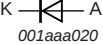
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	-	600	V
I _{F(AV)}	average forward current	square-wave pulse; δ = 0.5; T _{mb} ≤ 126 °C; see Figure 1 ; see Figure 2	-	-	5	A
Static characteristics						
V _F	forward voltage	I _F = 5 A; T _j = 25 °C; see Figure 5	-	1.3	1.9	V
		I _F = 5 A; T _j = 150 °C; see Figure 5	-	1.1	1.7	V
Dynamic characteristics						
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; see Figure 6	-	17.5	35	ns



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	K	mounting base; cathode		

SOD59 (TO-220AC)

3. Ordering information

Table 3. Ordering information

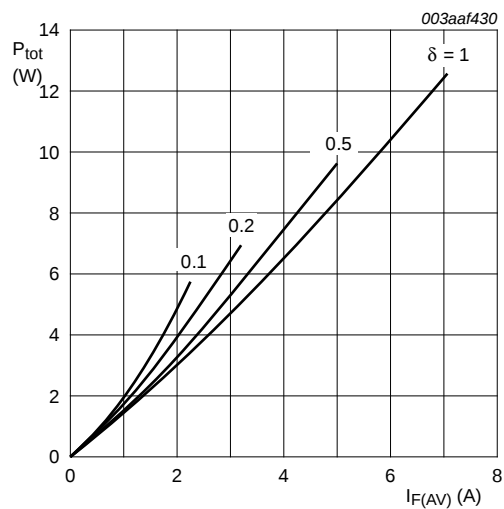
Type number	Package		
	Name	Description	Version
BYV25F-600	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

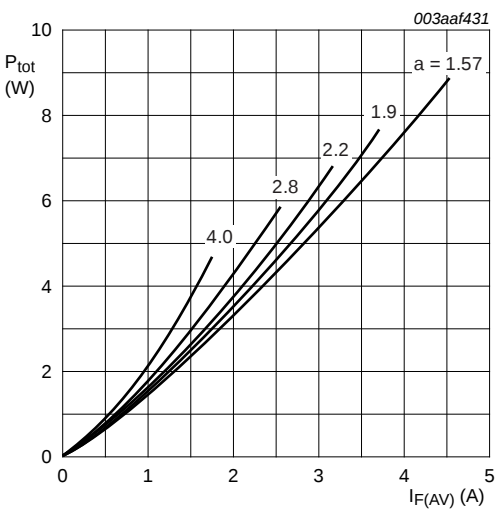
Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	600	V
V_{RWM}	crest working reverse voltage		-	600	V
V_R	reverse voltage	DC	-	600	V
$I_{F(AV)}$	average forward current	square-wave pulse; $\delta = 0.5$; $T_{mb} \leq 126\text{ }^{\circ}\text{C}$; see Figure 1 ; see Figure 2	-	5	A
I_{FRM}	repetitive peak forward current	square-wave pulse; $\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 126\text{ }^{\circ}\text{C}$	-	10	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; sine-wave pulse; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; see Figure 3	-	60	A
		$t_p = 8.3\text{ ms}$; sine-wave pulse; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; see Figure 3	-	66	A
T_{stg}	storage temperature		-40	150	$^{\circ}\text{C}$
T_j	junction temperature		-	150	$^{\circ}\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$V_o = 1.499 \text{ V}; R_s = 0.041 \text{ } \Omega$

Fig 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$V_o = 1.499 \text{ V}; R_s = 0.041 \text{ } \Omega$

Fig 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

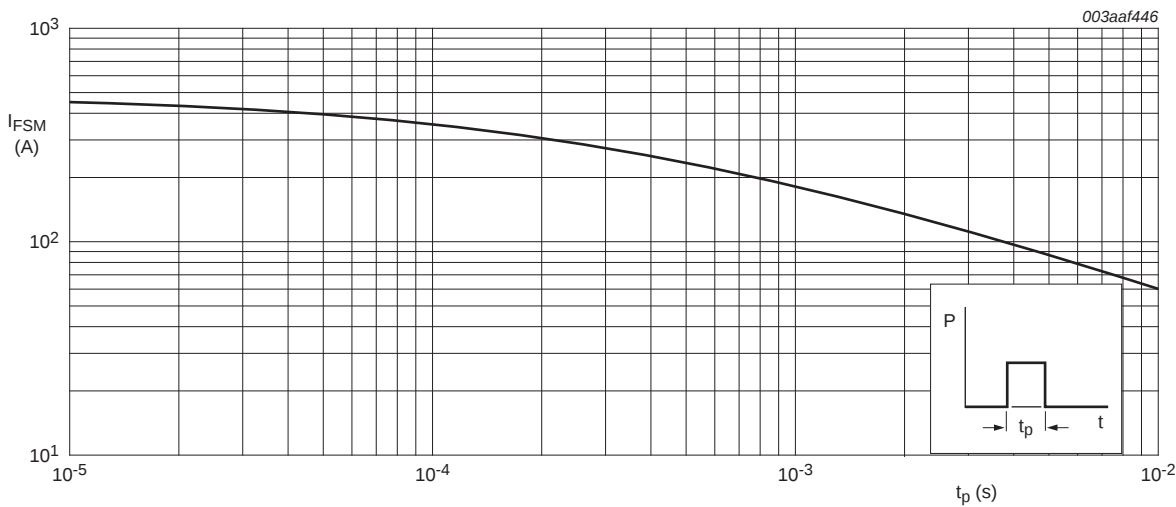


Fig 3. Non-repetitive peak forward current as a function of pulse width; square waveform; maximum values

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	2.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

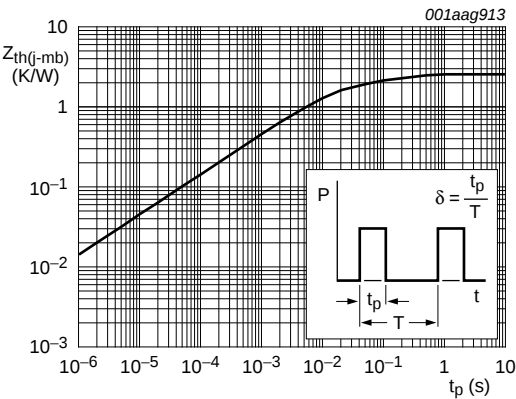
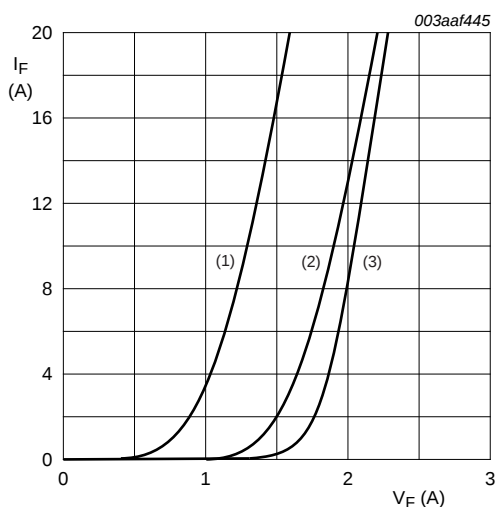


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse width

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _F	forward voltage	I _F = 5 A; T _j = 25 °C; see Figure 5	-	1.3	1.9	V
		I _F = 5 A; T _j = 150 °C; see Figure 5	-	1.1	1.7	V
I _R	reverse current	V _R = 600 V; T _j = 100 °C	-	-	1.5	mA
		V _R = 600 V; T _j = 25 °C	-	-	50	μA
Dynamic characteristics						
Q _r	recovered charge	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; see Figure 6	-	13	-	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; see Figure 6	-	17.5	35	ns
I _{RM}	peak reverse recovery current	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; see Figure 6	-	1.5	-	A
V _{FRM}	forward recovery voltage	I _F = 1 A; dI _F /dt = 100 A/μs; T _j = 25 °C; see Figure 7	-	3.2	-	V



$V_o = 1.499\text{ V}$; $R_s = 0.041\text{ }\Omega$

- (1) $T_j = 150\text{ °C}$; typical values;
- (2) $T_j = 150\text{ °C}$; maximum values;
- (3) $T_j = 25\text{ °C}$; maximum values;

Fig 5. Forward current as a function of forward voltage

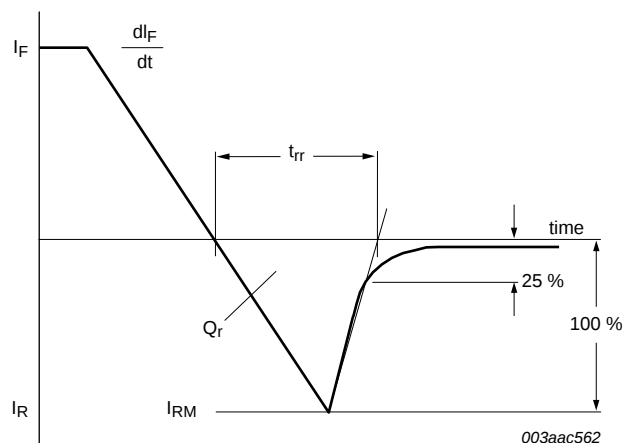


Fig 6. Reverse recovery definitions; ramp recovery

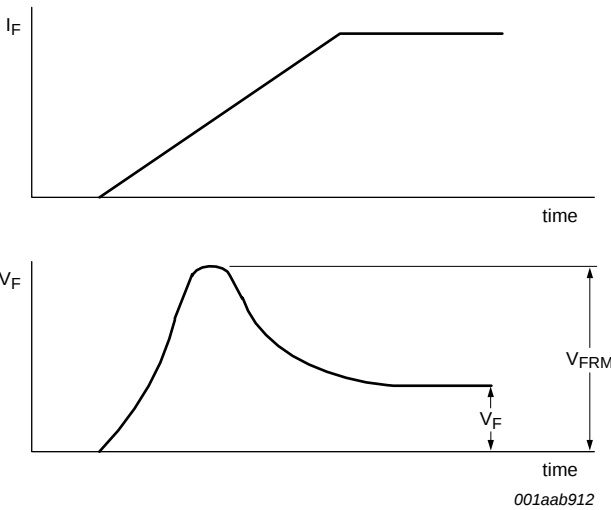
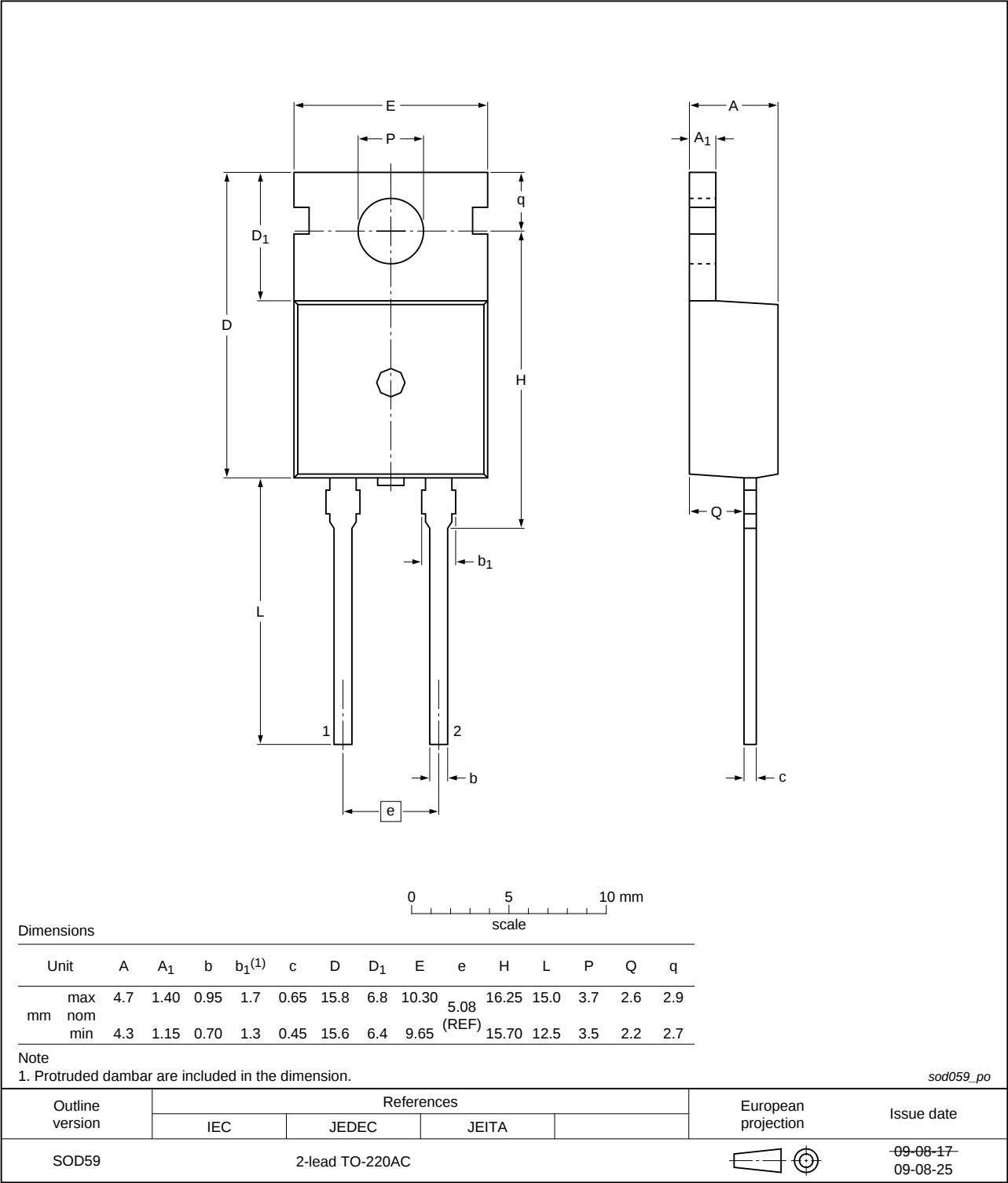


Fig 7. Forward recovery definitions

7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

SOD59



8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYV25F-600 v.2	20110307	Product data sheet	-	BYV25F-600 v.1
Modifications:	• Various changes to content.			
BYV25F-600 v.1	20101001	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1] [2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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